

RoHS Compliance Material Declaration Report

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Part Detail					
Pericom Part Number	Manufacturer part description	Package Type	Number of Pin/Terminal	Component overall weight	
P17C8150AND	2-Port PCI Bridge	PBGA (17x17)	256	0.7639	

RoHS Compliance		
Is Part compliant to EU RoHS Directive? <i>[1] Yes, [2] Yes with tech exemption* [3] Yes but needs product application exemption* [4] No</i>	RoHS tech exemption [2] details.	Date Component was RoHS Compliant.
[2] Yes with tech exemption	Pb in solder for nework infrastructure equipment	Since Inception

Content of RoHS restricted materials (g)						
Lead	Cadmium	Mercury	Hexavalent Chromium	Polybrominated biphenyls (PBB)	Polybrominated Diphenylethers (PBDE)	RoHS restricted substance added intentionally? For what reason?
0.06623	0	0	0	0	0	Yes - Termination alloy

Component Soldering Process						
Interconnect Composition, (Metallurgy of the lead/terminal)	JEDEC JEDS97 Pb-free Category	Compatible with a 260C 10s Pb-Free assembly process	Backward compatible with SnPb assembly	Maximum Processing Temperature (°C)	Max Temperature Duration	Max Number of reflow cycles
Sn/Pb(63/37%)	N/A	No	N/A	240	30	3

Plastics (if applicable)			
Oxygen Index	Type of plastic material used in the component	Fire: UL Rating	MSL Level (per JEDEC STD 020C)
>28%	Epoxy resin	V-0	3

Tin (Sn) Plating (If Applicable)					
Tin (Sn) Plating – is it Matte (M) or Bright (B)?	Tin (Sn) Plating Thickness	Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No	Nickel Barrier Thickness	If no Nickel barrier is the tin (Sn) termination finish heat treated?	Performed Tin Whisker Test ?
N/A	N/A	N/A	N/A	N/A	N/A

Bismuth (Bi)
Bismuth (Bi) Content (if applicable)
0